

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Sridhar Krishnamurthi Siddhamalli	07/20/2010
Mark W. Simon	08/02/2010
Michael E. Cahill	07/22/2010
RECEIVING PARTY DATA	
Name:	SAINT-GOBAIN PERFORMANCE PLASTICS CORPORATION
Street Address:	1199 South Chillicothe Road
City:	Aurora
State/Country:	OHIO
Postal Code:	44202
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12830226
CORRESPONDENCE DATA	
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Address Line 4:	Austin, TEXAS 78730
ATTORNEY DOCKET NUMBER:	1035-OFS6001-US
NAME OF SUBMITTER:	Jeffrey S. Abel

Total Attachments: 4
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CH \$40.00 12830226

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**PATENT
 REEL: 025015 FRAME: 0924**

ASSIGNMENT OF INVENTION

For good and valuable consideration, the receipt of which is hereby acknowledged, I, an Assignor named below,

Sridhar Krishnamurthi Siddhamalli of Lutz, FL 33558 USA

Mark W. Simon of Pascoag, RI 02859 USA

Michael E. Cahill of Waunakee, WI 53597 USA

hereby sell, assign and transfer to

ASSIGNEE: SAINT-GOBAIN PERFORMANCE PLASTICS CORPORATION, a California Corporation, having a principal place of business at 1199 South Chillicothe Road, Aurora, Ohio 44202, USA,

its successors, assigns and legal representatives, my entire right, title and interest throughout the world, including all rights to claim priority, in and to the invention disclosed in:

- U.S. Patent Application executed on or about the date of this Assignment,
- U.S. Patent Application executed on _____,
- U.S. Provisional Application _____, filed on _____,
- U.S. Application No.: 12/830,226, filed on July 2, 2010, or
- International Application No.: PCT/_____, filed on _____.

ENTITLED: **SEALABLE MATERIAL AND METHOD OF FORMING A DIELECTRIC WELD**, and naming as

INVENTOR(S): Sridhar Krishnamurthi Siddhamalli, Mark W. Simon, and Michael E. Cahill.

("Invention") including without limitation, my entire right, title and interest in and to any and all United States and foreign applications (including international, regional and foreign national applications) for said Invention, including divisions, continuations, continuations-in-part, utility models, industrial designs, renewals, substitutes and extensions thereof, and in and to any and all patents, invention registrations, or other forms of protection ("Patents") of every country or region that may be granted or have been granted for said Invention, including any reissues and reexaminations thereof.

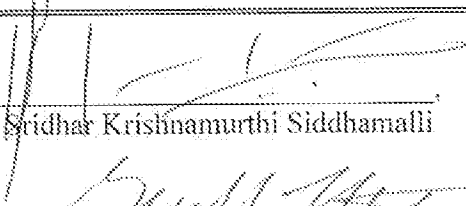
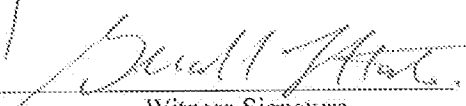
To comply with 37 C.F.R. § 3.21 for recording this Assignment, I authorize and request that the application number and filing date be inserted here, if not already shown above, (_____/_____, filed _____) when they become known.

I authorize Assignee to apply for patents in foreign countries for said Invention, and to claim all rights of priority without further authorization from me.

I agree that, upon request and without further compensation, but at no expense to me, I and/or my legal representatives and assigns will do all lawful acts, including the execution of papers and the giving of testimony, that may be necessary or desirable for obtaining, sustaining, reissuing, or enforcing the Patents in the United States and throughout the world for said Invention, and for perfecting, recording, or maintaining the title of Assignee, its successors and assigns, to said Invention, said application, and any Patents granted for said Invention in the United States and throughout the world.

I hereby covenant that no assignment, sale, license, agreement, or encumbrance has been or will be made or entered into that would conflict with this Assignment.

I authorize and request the Director of the United States Patent and Trademark Office and agencies, departments, or other similar offices and officials of all foreign countries to issue any Patents granted for said Invention, whether on said application or on any subsequently filed divisional, continuation, continuation-in-part, reexamination, reissue or other application, to Assignee, its successors and assigns, as the assignee of the entire interest in said Invention.

Executed on	July 20,	^{SES} 2010 300	by		Mridhar Krishnamurthi Siddhamalli
Witnessed on	July 20,	2010 300	by		Witness Signature

Executed on	_____	, 200	by	_____	Mark W. Simon
Witnessed on	_____	, 200	by	_____	Witness Signature

Executed on	_____	, 200	by	_____	Michael E. Cahill
Witnessed on	_____	, 200	by	_____	Witness Signature

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Executed on _____, 200__ by _____ Sridhar Krishnamurthi Siddhamalli
Witnessed on _____, 200__ by _____ Witness Signature

Executed on <u>Aug 2nd</u> , <u>2010</u> by <u>Mark W. Simon</u> Mark W. Simon
Witnessed on <u>Aug 2nd</u> , <u>2010</u> by <u>Kipeng Liu</u> Witness Signature

Executed on _____, 200__ by _____ Michael E. Cahill
Witnessed on _____, 200__ by _____ Witness Signature

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Executed on _____, 200__ by _____, Sridhar Krishnamurthi Siddhamalli
Witnessed on _____, 200__ by _____, Witness Signature

Executed on _____, 200__ by _____, Mark W. Simon
Witnessed on _____, 200__ by _____, Witness Signature

Executed on <u>22-JUL</u> , 20 <u>00</u> by <u>Michael E. Cahill</u> , Michael E. Cahill
Witnessed on <u>22-JULY</u> , 20 <u>00</u> by <u>[Signature]</u> , Witness Signature